Page 2 Dkt: 884.A74US1 (INTEL)

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Serial Number: 10/749,901 Filing Date: December 29, 2003

Title: INTEGRATED MICRO CHANNELS AND MANIFOLD/PLENUM USING SEPARATE SILICON OR LOW COST POLYCRYSTALLINE SILICON

Assignee: Intel Corporation

IN THE SPECIFICATION

Please amend the specification as follows:

On page 2, line 6, please add the following paragraph:

--Figure 9 is a perspective schematic view of an electronics system having a chip package and a silicon cooling plate.--